PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2997088

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HARRY HAK-LAY CHUANG	07/14/2014
CHENG-CHENG KUO	07/14/2014
CHING-CHE TSAI	07/14/2014
BAO-RU YOUNG	07/14/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14325693

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NAME OF SUBMITTER:	ERIC Q. LI
SIGNATURE:	/Eric Q. Li/
DATE SIGNED:	08/26/2014

Total Attachments: 2
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Docket No.: 2011-1007-CIP / 24061.2855
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Harry Hak-Lay Chuang of 51 Paya Lebar Crescent
Singapore 536191

(2) Cheng-Cheng Kuo of 7F., No. 127, Puding 3rd Rd., East District
Hsinchu City 300, Taiwan, R.O.C.

(3) Ching-Che Tsai of 15F, No. 93, Shengli 1st Road, Hsinchu County
Zhubei City 302, Taiwan, R.O.C.

(4) Bao-Ru Young of No. 7, Lane 1, Liujia 2nd Street, Hsinchu County
Zhubei City, 302, Taiwan, R.O.C.

have invented certain improvements in

REVISING LAYOUT DESIGN THROUGH OPC TO REDUCE CORNER ROUNDING EFFECT

for which we have filed an application for Letters Patent of the United States of America on July 8, 2014, and assigned U.S. Serial number 14/325,693; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Harry Hak-Lay Chuang

Residence Address: 51 Paya Lebar Crescent, Singapore 536176

✓Dated: 2014-7-14

✓

Inventor Signature

Inventor Name: Cheng-Cheng Kuo

Residence Address: 7F., No.127, Puding 3rd Rd., East District,
Hsinchu City 300, Taiwan, R.O.C.

✓Dated: 2014-7-14

✓ Cheng-Cheng Kuo

Inventor Signature

Inventor Name: Ching-Che Tsai

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Hsinchu County, Zhubei City 302, Taiwan, R.O.C.

✓Dated: 2014-7-14

✓ Ching-Che Tsai

Inventor Signature

Inventor Name: Bao-Ru Young

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✓Dated: 2014-7-14

✓ Bao-Ru Young

Inventor Signature